

**Application Data Sheet****Application Information**

Application Type::	Regular
Subject Matter::	Utility
CD-ROM or CD-R:	None
Title::	A METHOD OF PRODUCING A BONDED WAFER AND THE BONDED WAFER
Attorney Docket Number::	108868.01
Suggested Drawing Figure::	
Total Drawing Sheets::	4
Small Entity::	No

**Applicant Information**

Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Jun-ichiro
Family Name::	FURIHATA
City of Residence::	Gunma
Country of Residence::	Japan

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Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Kiyoshi
Family Name::	MITANI
City of Residence::	Gunma
Country of Residence::	Japan

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**Correspondence Information**

Correspondence Customer Number:: 25944

<b>Domestic Priority Information</b>			
Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application is a	Division of	09/787,038	3/13/2001
This Application is a	National Stage of	PCT/JP00/0434	7/11/2000
<b>Foreign Priority Information</b>			
Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	11/201585	7/15/99	Yes
<b>Assignee Information</b>			
Assignee Name::	Shin-Etsu Handotai Co., Ltd.		
Street of mailing address::	4-2, Marunouchi 1 -chome		
City of mailing address::	Tokyo		
State or Province of mailing address::	Chiyoda-ku		
Country of mailing address::	Japan		